Silicon Tuning Diodes

These devices are designed in the popular PLASTIC PACKAGE for high volume requirements of FM Radio and TV tuning and AFC, general frequency control and tuning applications. They provide solid-state reliability in replacement of mechanical tuning methods. Also available in Surface Mount Package up to 33pF.

- High Q
- Controlled and Uniform Tuning Ratio
- Standard Capacitance Tolerance — 10%
- Complete Typical Design Curves

### MAXIMUM RATINGS

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Symbol</th>
<th>MV21xx</th>
<th>MMBV21xxLT1</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Reverse Voltage</td>
<td>( V_R )</td>
<td>30</td>
<td>Vdc</td>
<td></td>
</tr>
<tr>
<td>Forward Current</td>
<td>( I_F )</td>
<td>200</td>
<td>mAdc</td>
<td></td>
</tr>
<tr>
<td>Forward Power Dissipation @ ( T_A = 25^\circ C )</td>
<td>( P_D )</td>
<td>280</td>
<td>225</td>
<td>mW</td>
</tr>
<tr>
<td>Derate above 25°C</td>
<td></td>
<td>2.8</td>
<td>1.8</td>
<td>mW/°C</td>
</tr>
<tr>
<td>Junction Temperature</td>
<td>( T_J )</td>
<td></td>
<td>+150</td>
<td>ºC</td>
</tr>
<tr>
<td>Storage Temperature Range</td>
<td>( T_{stg} )</td>
<td>–55 to +150</td>
<td>ºC</td>
<td></td>
</tr>
</tbody>
</table>

### DEVICE MARKING

- MMBV2101LT1 = M4G
- MMBV2103LT1 = 4H
- MMBV2105LT1 = 4U
- MMBV2107LT1 = 4W
- MMBV2108LT1 = 4X
- MMBV2109LT1 = 4J

### ELECTRICAL CHARACTERISTICS (\( T_A = 25^\circ C \) unless otherwise noted)

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Symbol</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Reverse Breakdown Voltage ( (I_R = 10 , \mu A dc) )</td>
<td>( V_{(BR)R} )</td>
<td>30</td>
<td></td>
<td></td>
<td>Vdc</td>
</tr>
<tr>
<td>Reverse Voltage Leakage Current ( (V_R = 25 , V dc, T_A = 25^\circ C) )</td>
<td>( I_R )</td>
<td></td>
<td></td>
<td>0.1</td>
<td>µAdc</td>
</tr>
<tr>
<td>Diode Capacitance Temperature Coefficient ( (V_R = 4.0 , V dc, f = 1.0 , MHz) )</td>
<td>( T_{CC} )</td>
<td></td>
<td>280</td>
<td></td>
<td>ppm/°C</td>
</tr>
</tbody>
</table>

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PARAMETER TEST METHODS

1. **C<sub>T</sub>, DIODE CAPACITANCE**
   
   \( C_T = C_C + C_J \). \( C_T \) is measured at 1.0 MHz using a capacitance bridge (Boonton Electronics Model 75A or equivalent).

2. **TR, TUNING RATIO**
   
   TR is the ratio of \( C_T \) measured at 2.0 Vdc divided by \( C_T \) measured at 30 Vdc.

3. **Q, FIGURE OF MERIT**
   
   \( Q \) is calculated by taking the G and C readings of an admittance bridge at the specified frequency and substituting in the following equations:
   
   \[
   Q = \frac{2\pi f C}{G}
   \]
   
   (Boonton Electronics Model 33AS8 or equivalent). Use Lead Length = 1/16".

4. **TC<sub>C</sub>, DIODE CAPACITANCE TEMPERATURE COEFFICIENT**
   
   TC<sub>C</sub> is guaranteed by comparing \( C_T \) at \( V_R = 4.0 \) Vdc, \( f = 1.0 \) MHz, \( T_A = -65^\circ \)C with \( C_T \) at \( V_R = 4.0 \) Vdc, \( f = 1.0 \) MHz, \( T_A = +85^\circ \)C in the following equation, which defines TC<sub>C</sub>:
   
   \[
   TC_C = \left( \frac{C_T(+85^\circ \text{C}) - C_T(-65^\circ \text{C})}{85 + 65}\right) \times \frac{10^6}{C_T(25^\circ \text{C})}
   \]
   
   Accuracy limited by measurement of \( C_T \) to \( \pm 0.1 \) pF.
Figure 1. Diode Capacitance versus Reverse Voltage

Figure 2. Normalized Diode Capacitance versus Junction Temperature

Figure 3. Reverse Current versus Reverse Voltage

Figure 4. Figure of Merit versus Reverse Voltage

Figure 5. Figure of Merit versus Frequency
Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.

### POWER DISSIPATION FOR A SURFACE MOUNT DEVICE

The power dissipation for a surface mount device is a function of the pad size. These can vary from the minimum pad size for soldering to the pad size given for maximum power dissipation. Power dissipation for a surface mount device is determined by $T_{J\text{(max)}}$, the maximum rated junction temperature of the die, $R_{\theta JA}$, the thermal resistance from the device junction to ambient; and the operating temperature, $T_A$. Using the values provided on the data sheet, $P_D$ can be calculated as follows.

$$P_D = \frac{T_{J\text{(max)}} - T_A}{R_{\theta JA}}$$

The values for the equation are found in the maximum ratings table on the data sheet. Substituting these values into the equation for an ambient temperature $T_A$ of 25°C, one can calculate the power dissipation of the device. For example, for a SOT–23 device, $P_D$ is calculated as follows.

$$P_D = \frac{150°C - 25°C}{556°C/W} = 225 \text{ milliwatts}$$

### SOLDERING PRECAUTIONS

The melting temperature of solder is higher than the rated temperature of the device. When the entire device is heated to a high temperature, failure to complete soldering within a short time could result in device failure. Therefore, the following items should always be observed in order to minimize the thermal stress to which the devices are subjected.

- Always preheat the device.
- The delta temperature between the preheat and soldering should be 100°C or less.*
- When preheating and soldering, the temperature of the leads and the case must not exceed the maximum temperature ratings as shown on the data sheet. When using infrared heating with the reflow soldering method, the difference should be a maximum of 10°C.
- The soldering temperature and time should not exceed 260°C for more than 10 seconds.
- When shifting from preheating to soldering, the maximum temperature gradient should be 5°C or less.
- After soldering has been completed, the device should be allowed to cool naturally for at least three minutes. Gradual cooling should be used as the use of forced cooling will increase the temperature gradient and result in latent failure due to mechanical stress.
- Mechanical stress or shock should not be applied during cooling

* Soldering a device without preheating can cause excessive thermal shock and stress which can result in damage to the device.
Prior to placing surface mount components onto a printed circuit board, solder paste must be applied to the pads. A solder stencil is required to screen the optimum amount of solder paste onto the footprint. The stencil is made of brass or stainless steel with a typical thickness of 0.008 inches. The stencil opening size for the surface mounted package should be the same as the pad size on the printed circuit board, i.e., a 1:1 registration.

**TYPICAL SOLDER HEATING PROFILE**

For any given circuit board, there will be a group of control settings that will give the desired heat pattern. The operator must set temperatures for several heating zones, and a figure for belt speed. Taken together, these control settings make up a heating “profile” for that particular circuit board. On machines controlled by a computer, the computer remembers these profiles from one operating session to the next. Figure 6 shows a typical heating profile for use when soldering a surface mount device to a printed circuit board. This profile will vary among soldering systems but it is a good starting point. Factors that can affect the profile include the type of soldering system in use, density and types of components on the board, type of solder used, and the type of board or substrate material being used. This profile shows temperature versus time. The line on the graph shows the actual temperature that might be experienced on the surface of a test board at or near a central solder joint. The two profiles are based on a high density and a low density board. The Vitronics SMD310 convection/infrared reflow soldering system was used to generate this profile. The type of solder used was 62/36/2 Tin Lead Silver with a melting point between 177 –189°C. When this type of furnace is used for solder reflow work, the circuit boards and solder joints tend to heat first. The components on the board are then heated by conduction. The circuit board, because it has a large surface area, absorbs the thermal energy more efficiently, then distributes this energy to the components. Because of this effect, the main body of a component may be up to 30 degrees cooler than the adjacent solder joints.

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**Figure 6. Typical Solder Heating Profile**

- **Step 1** Preheat Zone 1 “Ramp”
- **Step 2** Vent “Soak”
- **Step 3** Heating Zones 2 & 5 “Ramp”
- **Step 4** Heating Zones 3 & 6 “Soak”
- **Step 5** Heating Zones 4 & 7 “Spike”
- **Step 6** Vent
- **Step 7** Cooling

Temperature ranges:
- **205°C to 219°C** Peak at Solder Joint
- **170°C**
- **160°C**
- **150°C**
- **140°C**
- **130°C**
- **120°C**
- **110°C**
- **100°C**
- **90°C**
- **80°C**
- **70°C**
- **60°C**
- **50°C**

Desired curve for high mass assemblies:
- **170°C**
- **160°C**
- **150°C**

Desired curve for low mass assemblies:
- **100°C**

Time (3 to 7 minutes total)
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MMBV2109LT1 MVB2101 MVB2104 MVB2108 MVB2109 MV2111 MV2115

PACKAGE DIMENSIONS

NOTES:
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

STYLE B:
1. PIN 1, ANODE
2. NO CONNECTION
3. CATHODE

CASE 318–08
ISSUE AE
SOT–23 (TO–236AB)

SECTION X–X
STYLE 1:
1. PIN 1, ANODE
2. CATHODE

CASE 182–02
(TO–226AC)
ISSUE H

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